

REMARKS

Claims 1-5 and 9-16 are now pending in the application. By this paper, Claims 2 and 13 have been amended and Claims 6-8 and 17-19 have been cancelled without prejudice or disclaimer of the subject matter contained therein. The basis for these amendments can be found throughout the specification, claims, and drawings originally filed. No new matter has been added. The preceding amendments and the following remarks are believed to be fully responsive to the outstanding Office Action and are believed to place the application in condition for allowance.

The Examiner is respectfully requested to reconsider and withdraw the rejections in view of the amendments and remarks contained herein.

INFORMATION DISCLOSURE STATEMENT

The Examiner states that the Information Disclosure Statement filed April 5, 2005 fails to comply with the requirements of 37 C.F.R. §§ 1.98(a)(1) and (b)(3). Specifically, the Examiner states that the Information Disclosure Statement fails to identify each U.S. application by inventor, application number, and filing date and that a list of all patents, publications, applications, or other information submitted for consideration by the Office is lacking.

The Information Disclosure Statement filed on April 5, 2005 does not include a list of U.S. patents and/or publications or a corresponding list identifying inventor, application number, and filing date as the Information Disclosure Statement was filed simply to cross reference a related application. Specifically, Applicants direct the Examiner to Section Four of the Information Disclosure Statement, which cross

references the present application to Application No. 10/791,651 filed March 2, 2004. Because the Information Disclosure Statement was filed merely to cross reference the present application with Application No. 10/791,651, Applicants respectfully submit that the Information Disclosure Statement is in proper form as filed. Accordingly, Applicants respectfully request that the Examiner consider, and enter into the Record, the Information Disclosure Statement filed April 5, 2005.

CLAIM OBJECTIONS

Claims 2 and 13 have been amended in accordance with the Examiner's requirement. Specifically, each of Claims 2 and 13 now recite "wherein a polyimide precursor is used as the thermal setting resin precursor and is polymerized by the heat." Because Claims 2 and 13 have been amended to correct the typographical error at line 3 of each claim, Applicants respectfully submit that Claims 2 and 13 are in condition for allowance.

REJECTION UNDER 35 U.S.C. § 102

Claims 1, 2, 4, 9, 13 and 15 stand rejected under 35 U.S.C. § 102(b) as being anticipated by Yoshinuma et al. (U.S. Pat. No. 6,378,199).

This rejection is respectfully traversed.

Independent Claim 1 calls for a method of manufacturing a wiring board including forming a receiving layer from a thermal setting resin precursor, forming an interconnecting layer on the receiving layer from a dispersion liquid containing conductive particles, and applying heat to the receiving layer and the interconnecting

layer to cure the thermal setting resin precursor and to bond the conductive particles together.

Independent Claim 9 calls for a method of manufacturing a wiring board including forming a first receiving layer from a thermal setting resin precursor, forming a first interconnecting layer on the first receiving layer from a dispersion liquid containing conductive particles, and forming a second receiving layer on the first receiving layer and the first interconnecting layer from a thermal setting resin precursor. Independent Claim 9 further calls for forming a second interconnecting on the second receiving layer from a dispersion liquid containing conductive particles and applying heat to cure the thermal setting resin precursors of the first and second receiving layers and to bond the conductive particles of the first and second interconnecting layers together at a connecting portion of the first and second interconnecting layers.

In this manner, each of independent Claims 1 and 9 calls for a method of manufacturing a wiring board including forming an interconnecting layer on a receiving layer from a dispersion liquid containing conductive particles. The conductive particles disposed within the dispersion liquid form a conductive layer on the receiving layer to produce a highly reliable wiring board.

Yoshinuma fails to teach forming an interconnecting layer on a receiving layer from a dispersion liquid containing conductive particles. Yoshinuma teaches a multi-layer printed-wiring board (1) having a substrate (2), a first wiring pattern (3), a second wiring pattern layer (4), and a third wiring pattern layer (5). See Yoshinuma at Column 8, Lines 51-60. Each wiring pattern layer (3, 4, 5) includes an electrically conductive layer (3a, 4a, 5a) and an electrically insulating resin layer (3b, 4b, 5b) formed under the

conductive layer. See Yoshinuma at Column 8, Lines 61-64. Yoshinuma further teaches that the wiring pattern layer (3) may intercept the wiring pattern layer (4) to produce a multi-layer printed-wiring board (1) as shown in Figure 12. Yoshinuma notes that the connection between the wiring layers may be accomplished by any one of 14 methods described at Column 17, Lines 6-17. Among the 14 methods noted, Yoshinuma notes that the wiring pattern layer (3) may be *connected to* the wiring pattern layer (4) by a dispensing method or a printing method, but fails to teach that the wiring pattern layer (3) or the wiring pattern layer (4) is formed on the substrate by using a dispersion liquid containing conductive particles.

Because Yoshinuma fails to teach forming an interconnecting layer on a receiving layer from a dispersion liquid containing conductive particles, Applicants respectfully submit that Yoshinuma fails to teach each and every element of the present invention. Accordingly, Applicants respectfully submit that independent Claims 1 and 9, as well as Claims 2, 4, 13, and 15, respectively dependent therefrom, are in condition for allowance. Therefore, reconsideration and withdrawal of the rejection is respectfully requested.

REJECTION UNDER 35 U.S.C. § 103

Claims 3, 10-12 and 14 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Yoshinuma et al. (U.S. Pat. No. 6,378,199). This rejection is respectfully traversed.

Independent Claims 1 and 9 are believed to be in condition for allowance in light of the remarks contained above. Because Claims 3, 10-12, and 14, respectively depend from independent Claims 1 and 9, dependent Claims 3, 10-12, and 14 should similarly be in a condition for allowance for at least the same reasons. Therefore, reconsideration and withdrawal of the rejection is respectfully requested.

ALLOWABLE SUBJECT MATTER

The Examiner states that Claims 5 and 16 would be allowable if rewritten in independent form. Applicants have not amended independent Claims 1 and 16 to include the allowable subject matter of Claims 5 and 6, respectively, as independent Claims 1 and 9 are believed to be in condition for allowance in their present form in light of the foregoing remarks.

CONCLUSION

It is believed that all of the stated grounds of rejection have been properly traversed, accommodated, or rendered moot. Applicants therefore respectfully request that the Examiner reconsider and withdraw all presently outstanding rejections. It is believed that a full and complete response has been made to the outstanding Office Action and the present application is in condition for allowance. Thus, prompt and

favorable consideration of this amendment is respectfully requested. If the Examiner believes that personal communication will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at (248) 641-1600.

Respectfully submitted,

Dated: March 13, 2006

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